**IN THE CLAIMS**

Please amend the claims as follows:

1. (Currently amended) A semiconductor integrated circuit device including a digital circuit and an analog circuit which are integrated on a single semiconductor chip, said device comprising:

a first electrostatic destruction protection circuit, connected to the digital circuit, for protecting the digital circuit from destruction caused by electrostatic discharge ~~ESD~~ in the digital circuit by an influence of an input digital signal; ~~and~~

a second electrostatic destruction protection circuit, connected to the analog circuit, for protecting the analog circuit from destruction caused by electrostatic discharge ~~ESD~~ in the analog circuit by an influence of an input analog signal,

a first power supply pad for supplying a digital ground source to the first electrostatic destruction protection circuit; and

a second power supply pad for supplying an analog ground source to the second electrostatic destruction protection circuit,

wherein a first grounding conductor connected to the first electrostatic destruction protection circuit and a second grounding conductor connected to the second electrostatic destruction protection circuit are connected to each other outside the semiconductor integrated circuit device via the first power supply pad and the second power supply pad.

2. (Original) The semiconductor integrated circuit device of claim 1, wherein the first grounding conductor and the second grounding conductor are connected to each other inside a package substrate of the semiconductor integrated circuit device.

3. (Original) The semiconductor integrated circuit device of claim 1, wherein the first grounding conductor and the second grounding conductor are connected to each other outside a package substrate of the semiconductor integrated circuit device.

4. (Original) The semiconductor integrated circuit device of claim 1, wherein the first grounding conductor and the second grounding conductor are connected to each other using a capacitance outside a package substrate of the semiconductor integrated circuit device.

5. (Original) The semiconductor integrated circuit device of claim 1, wherein the first grounding conductor and the second grounding conductor are connected to each other via a member for electrically connecting the semiconductor integrated circuit device to a package substrate of the semiconductor integrated circuit device.

6-11. (Canceled)